

IPC-4101 /24 /121 /124 UL - File Number E41625

FR408 is a high-performance FR-4 epoxy laminate and prepreg system designed for advanced circuitry applications.

PRODUCT FEATURES

Industry Recognition

- UL File Number: E41625
- Qualified to UL's MCIL Program
- RoHS Compliant

Performance Attributes

Processing Advantages

- FR-4 process compatible
- UV blocking and AOI fluorescence

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 125 mil (0.05 to 3.2 mm)
- Available in full size sheet or panel form

Copper Foil Type

- HTE Grade 3
- RTF (Reverse Treat Foil)

Copper Weight

- ½ to 2 oz (18 to 70 µm) available
- Heavier copper available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Roll or panel form
- Tooling of prepreg panels

Glass Fabric Availability

- E-glass
- Square weave glass

Its low dielectric constant (Dk) and low dissipation factor (Df) make it an ideal candidate for broadband circuit designs requiring faster signal speeds or improved signal integrity. FR408 is compatible with most FR-4 processes. This feature allows the use of FR408 without adding complexity to current fabrication techniques.

PRODUCT ATTRIBUTES



TYPICAL MARKET APPLICATIONS



Typical Values Table

Property	Typical Value	Units		Test Method
		Metric (English)		IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC	180		°C	2.4.25C
Decomposition Temperature (Td) by TGA @ 5% weight loss	360		°C	2.4.24.6
Time to Delaminate by TMA (Copper removed)	A. T260 B. T288	60 15	Minutes	2.4.24.1
Z-Axis CTE	A. Pre-Tg B. Post-Tg C. 50 to 260°C, (Total Expansion)	60 228 3.5	ppm/°C ppm/°C %	2.4.24C
X/Y-Axis CTE	Pre-Tg	13	ppm/°C	2.4.24C
Thermal Conductivity		0.4	W/m-K	ASTM E1952
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched B. Etched	Pass	Pass Visual	2.4.13.1
Dk, Permittivity	A. @ 100 MHz B. @ 1 GHz C. @ 2 GHz D. @ 5 GHz E. @ 10 GHz	3.69 3.66 3.67 3.66 3.65	—	2.5.5.3 2.5.5.9 Bereskin Stripline Bereskin Stripline Bereskin Stripline
Df, Loss Tangent	A. @ 100 MHz B. @ 1 GHz C. @ 2 GHz D. @ 5 GHz E. @ 10 GHz	0.0094 0.0117 0.0120 0.0127 0.0125	—	2.5.5.3 2.5.5.9 Bereskin Stripline Bereskin Stripline Bereskin Stripline
Volume Resistivity	A. After moisture resistance B. At elevated temperature	4.6×10^7 2.8×10^8	MΩ-cm	2.5.17.1
Surface Resistivity	A. After moisture resistance B. At elevated temperature	2.81×10^6 2.64×10^8	MΩ	2.5.17.1
Dielectric Breakdown		>50	kV	2.5.6B
Arc Resistance		120	Seconds	2.5.1B
Electric Strength (Laminate & laminated prepreg)		55 (1400)	kV/mm (V/mil)	2.5.6.2A
Comparative Tracking Index (CTI)		3 (175-249)	Class (Volts)	UL 746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile copper foil all copper foil >17 μm [0.669 mil] B. Standard profile copper 1. After thermal stress 2. At 125°C (257°F) 3. After process solutions	1.14 (6.5) 1.225 (7.0) 1.14 (6.5) 0.90 (5.1)	N/mm (lb/inch)	2.4.8C 2.4.8.2A 2.4.8.3 2.4.8.3
Flexural Strength	A. Length direction B. Cross direction	81.4 64.1	ksi	2.4.4B
Tensile Strength	A. Length direction B. Cross direction	59.3 42.0	ksi	ASTM D3039
Young's Modulus	A. Length direction B. Cross direction	3685 3044	ksi	ASTM D790-15e2
Poisson's Ratio	A. Length direction B. Cross direction	0.162 0.138	—	ASTM D3039
Moisture Absorption		0.15	%	2.6.2.1A
Flammability (Laminate & laminated prepreg)		V-0	Rating	UL 94
Relative Thermal Index (RTI)		130	°C	UL 796

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